

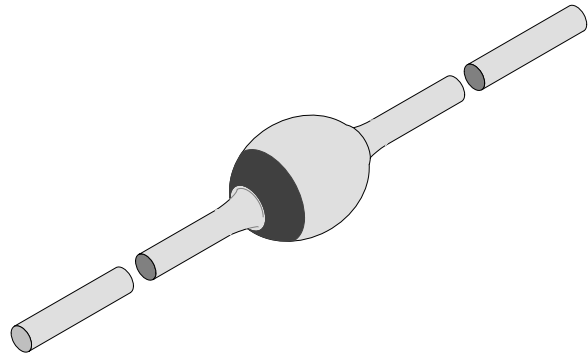
## Silicon Z-Diodes

### Features

- Glass passivated junction
- Hermetically sealed package
- Clamping time in picoseconds

### Applications

Medium power voltage regulators and medium power transient suppression circuits



94 9539

### Absolute Maximum Ratings

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Value	Unit
Power dissipation	$l=10\text{mm}, T_L=25^\circ\text{C}$		$P_V$	3.25	W
	$T_{\text{amb}}=25^\circ\text{C}$		$P_V$	1.3	W
Repetitive peak reverse power dissipation			$P_{ZRM}$	10	W
Non repetitive peak surge power dissipation	$t_p=100\mu\text{s}, T_j=25^\circ\text{C}$		$P_{ZSM}$	600	W
Junction temperature			$T_j$	175	$^\circ\text{C}$
Storage temperature range			$T_{\text{stg}}$	-65...+175	$^\circ\text{C}$

### Maximum Thermal Resistance

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Junction ambient	$l=10\text{mm}, T_L=\text{constant}$	$R_{\text{thJA}}$	46	K/W
	on PC board with spacing 25mm	$R_{\text{thJA}}$	100	K/W

### Characteristics

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F=0.5\text{A}$		$V_F$			1.2	V

### Characteristics when used as voltage regulator diodes, $T_j = 25^\circ\text{C}$

Type BZT03D...	$V_Z$ V			$r_{zj}$ $\Omega$		and $TK_{UZ}$ %/K		at $I_Z$ mA	$I_R$ $\mu\text{A}$	at $V_R$
	Min.	Typ.	Max.	Typ.	Max.	Min.	Max.		Max.	
6V2	5.6	6.2	6.8	1	2	0	0.07	100	1500	4.4
6V8	6.1	6.8	7.5	1	2	0	0.07	100	1000	4.8
7V5	6.75	7.5	8.25	1	2	0	0.07	100	750	5.3
8V2	7.4	8.2	9.0	1	2	0.03	0.08	100	600	5.9
9V1	8.2	9.1	10.0	2	4	0.03	0.08	50	20	6.5
10	9.0	10	11.0	2	4	0.05	0.09	50	10	7.1
11	9.9	11	12.1	4	7	0.05	0.10	50	4	7.9
12	10.8	12	13.2	4	7	0.05	0.10	50	3	8.6
13	11.7	13	14.3	5	10	0.05	0.10	50	2	9.3
15	13.5	15	16.5	5	10	0.05	0.10	50	1	10.6
16	14.4	16	17.6	6	15	0.06	0.11	25	1	11.6
18	16.2	18	19.8	6	15	0.06	0.11	25	1	12.6
20	18.0	20	22.0	6	15	0.06	0.11	25	1	14.4
22	29.8	22	24.2	6	15	0.06	0.11	25	1	15.8
24	21.6	24	26.4	7	15	0.06	0.11	25	1	17.2
27	24.3	27	29.7	7	15	0.06	0.11	25	1	19.4
30	27	30	33	8	15	0.06	0.11	25	1	21.5
33	29.7	33	36.3	8	15	0.06	0.11	25	1	23.5
36	32.4	36	39.6	21	40	0.06	0.11	10	1	25.8
39	35.1	39	42.9	21	40	0.06	0.11	10	1	28
43	38.7	43	47.3	24	45	0.07	0.12	10	1	31
47	42.3	47	51.7	24	45	0.07	0.12	10	1	33.5
51	45.9	51	56.1	25	60	0.07	0.12	10	1	36.5
56	50.4	56	61.6	25	60	0.07	0.12	10	1	40
62	55.8	62	68.2	25	80	0.08	0.13	10	1	44.5
68	61.2	68	74.8	25	80	0.08	0.13	10	1	49
75	67.5	75	82.5	30	100	0.08	0.13	10	1	54
82	73.8	82	90.2	30	100	0.08	0.13	10	1	59
91	81.9	91	100	60	200	0.09	0.13	5	1	65
100	90	100	110	60	200	0.09	0.13	5	1	71
110	99	110	121	80	250	0.09	0.13	5	1	79
120	108	120	132	80	250	0.09	0.13	5	1	86
130	117	130	143	110	300	0.09	0.13	5	1	93
150	135	150	165	130	300	0.09	0.13	5	1	106

## Characteristics when used as transient suppressor diodes, $T_j = 25^\circ\text{C}$

Type BZT03D...	$V_Z$ V			$r_{zj}$ $\Omega$		and $TK_{UZ}$ %/K		at $I_Z$ mA	$I_R$ $\mu\text{A}$	at $V_R$
	Min.	Typ.	Max.	Typ.	Max.	Min.	Max.		Max.	
160	144	160	176	150	350	0.09	0.13	5	1	116
180	162	180	198	180	400	0.09	0.13	5	1	126
200	180	200	220	200	500	0.09	0.13	5	1	144
220	198	220	242	350	750	0.09	0.13	2	1	158
240	216	240	264	400	850	0.09	0.13	2	1	172
270	243	270	297	450	1000	0.09	0.13	2	1	194

### Characteristics when used as transient suppressor diodes, $T_j = 25^\circ\text{C}$

Type BZT03D...	Clamping		Stand-off	
	$V_{(CL)R}^{1)}$ V	at $I_{RSM}$ A	$I_R$ $\mu\text{A}$	at $V_R^{2)}$ V
	Max.		Max.	
6V2	9.5	34.0	3000	4.8
6V8	10.5	31.0	2000	5.3
7V5	11.6	26.5	1500	5.9
8V2	12.6	24.4	1200	6.5
9V1	13.7	22.7	50	7.1
10	15.2	20.3	20	7.9
11	16.2	19.1	5	8.6
12	17.5	17.7	5	9.3
13	19.1	15.9	5	10.6
15	21.8	14.4	5	11.6
16	23.4	13.1	5	12.6
18	26.3	11.7	5	14.4
20	29.2	10.6	5	15.8
22	31.9	9.7	5	17.2
24	34.6	8.9	5	19.4
27	39	7.9	5	21.5
30	43.5	7.1	5	23.5
33	47.5	6.5	5	25.8
36	51.5	6.0	5	28
39	56	5.5	5	31
43	62	4.9	5	33.5
47	67.5	4.6	5	36.5
51	73	4.2	5	40
56	81	3.8	5	44.5
62	89	3.5	5	49
68	97	3.2	5	54
75	107	2.9	5	59
82	117	2.6	5	65
91	130	2.4	5	71
100	143	2.2	5	79
110	157	2.0	5	86
120	172	1.8	5	93
130	187	1.6	5	106
150	213	1.5	5	116
160	229	1.3	5	126

Type BZT03D...	Clamping		Stand-off			
	$V_{(CL)R}^{1)}$ V	at	$I_{RSM}$ A	$I_R$ $\mu A$	at	$V_R^{2)}$ V
	Max.			Max.		
180	256		1.2	5		144
200	284		1.1	5		158
220	314		1.0	5		172
240	364		0.9	5		194
270	388		0.8	5		215

1) 10/1000 exp. falling pulse  $t_p = 1000 \mu s$  down to 50%

2) Stand-off voltage = recommended supply voltage

## Typical Characteristics ( $T_j = 25^\circ C$ unless otherwise specified)

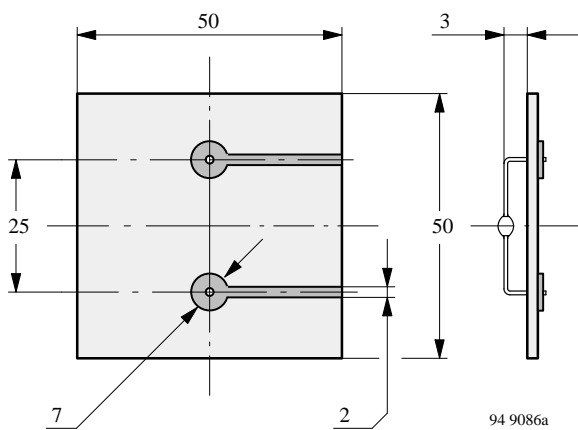


Figure 1 : Epoxy glass hard tissue, board thickness 1.5 mm,  
 $R_{thJA} \leq 100 K/W$

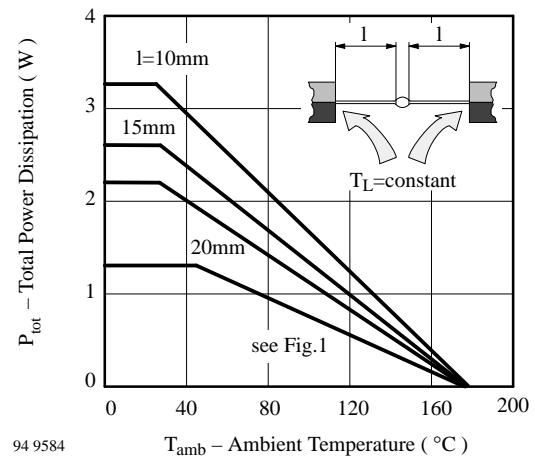


Figure 2 : Total Power Dissipation vs. Ambient Temperature

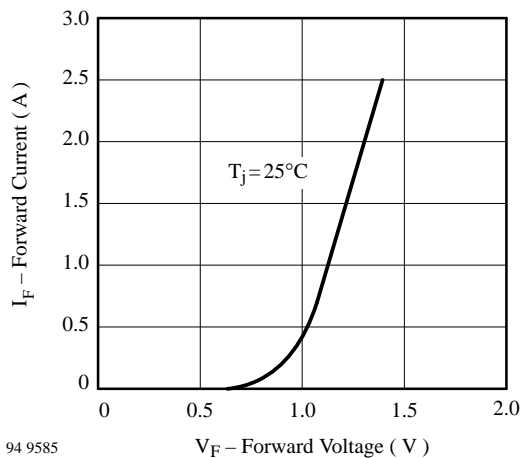


Figure 3 : Forward Current vs. Forward Voltage

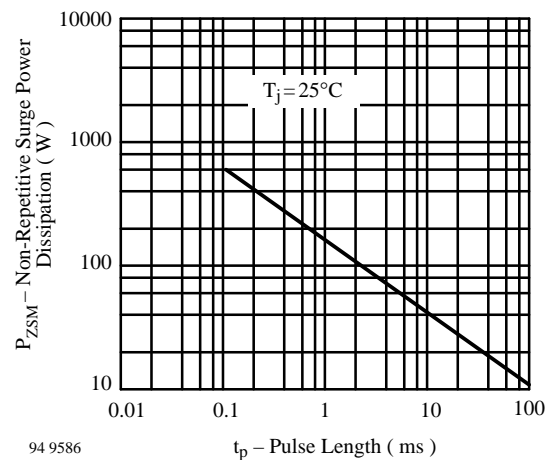



Figure 4 : Non Repetitive Surge Power Dissipation vs. Pulse Length

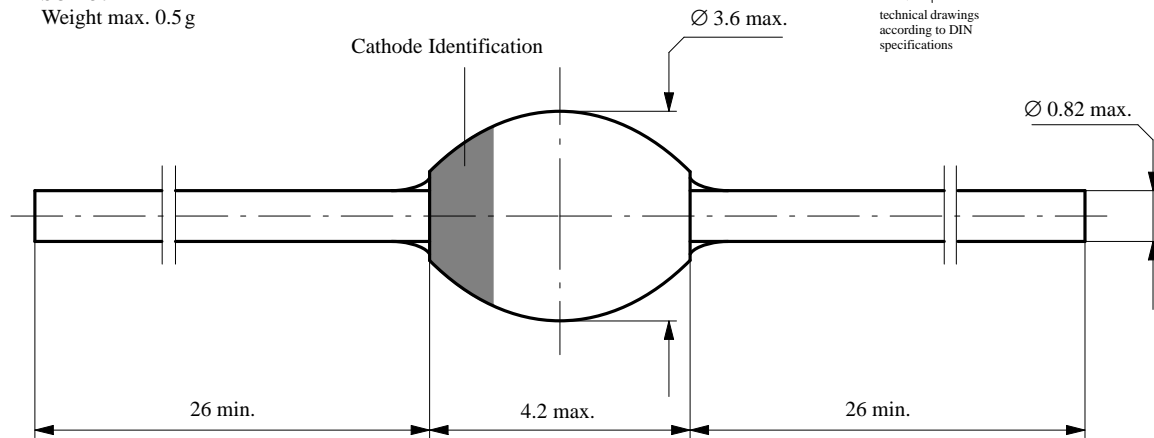
## BZT03D...

### Dimensions in mm

Sintered Glass Case  
SOD 57  
Weight max. 0.5 g

  
technical drawings  
according to DIN  
specifications

94 9538



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## OZONE DEPLETING SUBSTANCES POLICY STATEMENT

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1. Meet all present and future national and international statutory requirements and
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

Of particular concern is the control or elimination of releases into the atmosphere of those substances which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) will soon severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**TEMIC TELEFUNKEN microelectronic GmbH** semiconductor division has been able to use its policy of continuous improvements to eliminate the use of any ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA and
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**TEMIC** can certify that our semiconductors are not manufactured with and do not contain ozone depleting substances.

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